

**ABSTRACT OF THE DISCLOSURE**

A method and a system are provided for removing matter adhered to such a polishing pad. In particular, a polishing system is provided which is adapted to remove matter adhered to a polishing pad during a polishing process of a semiconductor topography. The polishing system may include a polishing pad and a spray element, which is preferably adapted to spray a pressurized fluid upon the polishing pad to remove matter adhered to the pad. In addition, a spray element is provided which may be adapted to be positioned within a polishing system. Such a spray element may be adapted to remove matter adhered to a polishing pad within the system by spraying a pressurized fluid upon the polishing pad. In addition, methods for cleaning a polishing pad during a polishing process and polishing multiple semiconductor topographies using the systems described herein are provided.

FD-302a (Rev. 1-25-60)